

FMSB40B THRU FMSB40M UMSB

4.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER Reverse Voltage - 100 to 1000 V Forward Current – 4.0A

FEATURES

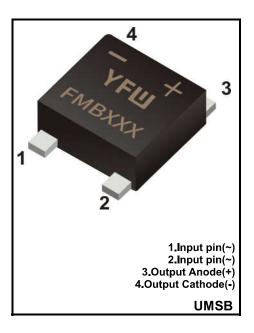
- ♦Fast reverse recovery time
- **♦**Designed for Surface Mount Application
- ♦Glass Passivated Chip Junction
- **♦Low power loss, high efficiency**
- ♦Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

♦Case: UMSB

♦Terminals: Solderable per MIL-STD-750, Method 2026

♦Approx. Weight: 0.234g / 0.00824oz



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FMSB40B	FMSB40D	FMSB40G	FMSB40J	FMSB40K	FMSB40M	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	v
Maximum RMS voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at T _c = 115 °C	I _o	4.0					Α	
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load(JEDEC method)	I _{FSM}	95					Α	
Forward Voltage per element at 4.0A	V _F	1.1				٧		
Maximum DC Reverse Current @T _A =25°C at Rated DC Blocking Voltage @T _A =125°C	I _R	5.0 200					μΑ	
Typical Junction Capacitance (Note1)	C _j	50			pF			
Maximum Reverse Recovery Time (Note2)	Trr		150		250	50	00	nS
Typical Thermal Resistance (Note3)	Reja Rejc Rejl	60 15 25					°C/W	
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ +150				°C		

⁽¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C

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⁽²⁾ Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

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Fig.1 Average Rectified Output Current Derating Curve

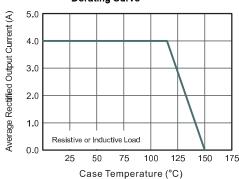


Fig.2 Typical Reverse Characteristics

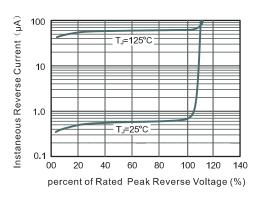


Fig.3 Typical Instaneous Forward Characteristics

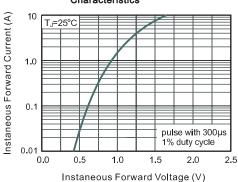


Fig.4 Typical Junction Capacitance

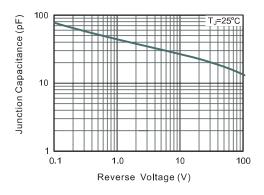


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

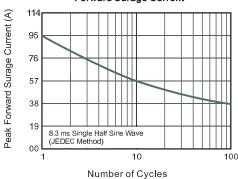
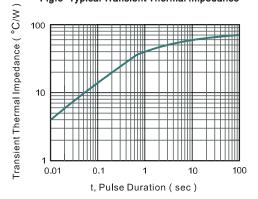
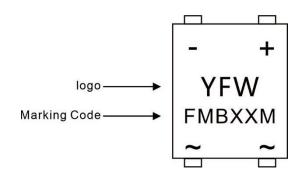


Fig.6- Typical Transient Thermal Impedance





Marking Diagram

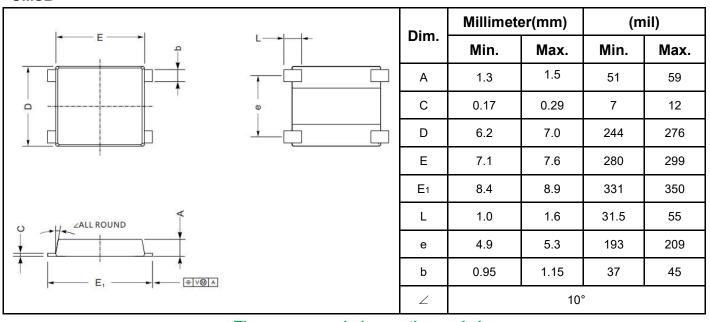


Ordering information

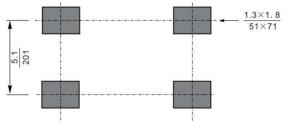
Package	Packing Description	Packing Quantity			
UMSB	Tape/Reel,13"reel	3000PCS/Reel 30000PCS/Carton			

Package Dimensions

UMSB



The recommended mounting pad size



Unit: mm (mil)





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